

2N7104 SERIES


N-Channel Lateral DMOS FETs

T-35-25

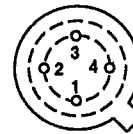
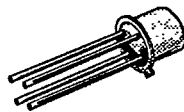
The 2N7104 Series of lateral DMOS FETs is designed for high speed switching in audio, video, and high-frequency applications. These devices are designed on the Siliconix DMOS process and utilize lateral construction to achieve low capacitance and ultra-fast switching speeds. For long term reliability this series features a polysilicon gate, making Siliconix 2N7104 devices the perfect choice for high-performance military applications.

PART NUMBER	$V_{(BR)DS}$ MAX (V)	$r_{ds(ON)}$ MAX (Ω)	C_{rss} MAX (pF)	t_{ON} MAX (ns)
2N7104	20	70	0.5	2
2N7106	10	70	0.5	2
2N7108	15	70	0.5	2

For additional design information please see performance curves DMCB, which are located in Section 7.

TO-72

BOTTOM VIEW



- 1 SOURCE
- 2 DRAIN
- 3 GATE
- 4 SUBSTRATE, CASE

SIMILAR PRODUCTS

- Quad Array, See 2N7116 Series
- SO-14 Array, See SD5400 Series
- Zener Protection, See 2N7105 Series
- SOT-143, See SST211 Series
- Chips, Order 2N710XCHP

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMIT			UNITS
		2N7104	2N7106	2N7108	
Gate-Source, Gate-Drain Gate-Substrate Voltage	V_{GS}, V_{GD}, V_{GB}	± 40	± 40	± 40	V
Drain-Source Voltage	V_{DS}	30	10	20	
Source-Drain Voltage	V_{SD}	10	10	20	
Drain-Substrate Voltage	V_{DB}	30	15	25	
Source-Substrate Voltage	V_{SB}	15	15	25	
Drain Current	I_D	50	50	50	mA
Power Dissipation ($T_J = 25^\circ\text{C}$)	P_D	300	300	300	mW
Power Derating		2.4	2.4	2.4	mW/ $^\circ\text{C}$
Operating Junction Temperature	T_J	-55 to 150			$^\circ\text{C}$
Storage Temperature	T_{stg}	-65 to 200			
Lead Temperature (1/16" from case for 10 seconds)	T_L	300			



2N7104 SERIES

ELECTRICAL CHARACTERISTICS ¹				LIMITS						
PARAMETER	SYMBOL	TEST CONDITIONS	TYP ²	2N7104		2N7106		2N7108		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
STATIC										
Drain-Source Breakdown Voltage ³	$V_{(BR)DS}$	$V_{GS} = V_{BS} = 0 V, I_D = 10 \mu A$	35	30						V
		$V_{GS} = V_{BS} = -5 V, I_S = 10 nA$	30	10		10		20		
Source-Drain Breakdown Voltage ³	$V_{(BR)SD}$	$V_{GD} = V_{BD} = -5 V, I_D = 10 nA$	22	10		10		20		
Drain-Substrate Breakdown Voltage ³	$V_{(BR)DB}$	$V_{GB} = 0 V$ $I_D = 10 nA$ Source OPEN	35	15		15		25		
Source-Substrate Breakdown Voltage ³	$V_{(BR)SB}$	$V_{GB} = 0 V$ $I_S = 10 \mu A$ Drain OPEN	35	15		15		25		
Drain-Source Leakage	$I_{DS(OFF)}$	$V_{GS} = V_{BS} = -5 V$ $T_A = 125^\circ C$	$V_{DS} = 10 V$	0.4		10		10		nA
			$V_{DS} = 20 V$	0.9					10	
Source-Drain Leakage	$I_{SD(OFF)}$	$V_{GD} = V_{BD} = -5 V$ $T_A = 125^\circ C$	$V_{SD} = 10 V$	0.5		10		10		nA
			$V_{SD} = 20 V$	1					10	
Gate Leakage	I_{GSS}	$V_{DS} = V_{SB} = 0 V$ $V_{GS} = 12 V$ $T_A = 125^\circ C$				100		100		100
						1		1		1
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 30 V, V_{GS} = V_{BS} = 0 V$				10				μA
Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS} = V_{GS(th)}, I_S = 1 \mu A$ $V_{SB} = 0 V$	0.7	0.5	2.0	0.1	2.0	0.1	2.0	V
Drain-Source On-Resistance	$r_{DS(ON)}$	$V_{GS} = 5 V, I_D = 1 mA$	58		70		70		70	Ω
DYNAMIC										
Forward Transconductance ³	g_{fs}	$V_{DS} = 10 V, V_{SB} = 0 V$ $I_D = 20 mA, f = 1 kHz$	11							mS
Output Conductance ³	g_{os}		0.9							
Gate Node Capacitance	C_{iss}	$V_{DS} = 10 V, f = 1 MHz$ $V_{GS} = V_{BS} = -15 V$	2.5		3.5		3.5		3.5	pF
Reverse Transfer Capacitance	C_{rss}		0.2		0.5		0.5		0.5	
SWITCHING										
Turn-ON Time	$t_d(ON)$	$V_{DD} = 5 V, R_L = 680 \Omega$ $V_{IN} = 5 V, R_G = 50 \Omega$	0.5		1		1		1	ns
	t_r		0.6		1		1		1	
Turn-OFF Time ³	$t_d(OFF)$		2							
	t_f		6							

- NOTES: 1. $T_A = 25^\circ C$ unless otherwise noted.
 2. For design aid only, not subject to production testing.
 3. This parameter not registered with JEDEC.

5